

What is claimed is:

1. A high frequency laminated device comprising:
a laminated body including
a first sheet having a relative permeability larger than
5 1,
a second sheet having a relative permeability larger
than 1 on a first surface of said first sheet, and
a third sheet provided over a second surface of said
first sheet;
10 a first inductor pattern forming a first inductor and provided
between said first and second sheets; and
first and second capacitor patterns forming a capacitor and
opposed to each other about said third sheet therebetween.
- 15 2. The high frequency laminated device of claim 1, wherein said third
sheet comprises a dielectric sheet.
3. The high frequency laminated device of claim 2, wherein said first
and third sheets are stacked and sintered after said first capacitor pattern is
20 printed at an interface between said first and third sheets.
4. The high frequency laminated device of claim 1, further comprising
a via-conductor formed in said first sheet, for electrically connecting said
first inductor pattern and said first capacitor pattern.
- 25 5. The high frequency laminated device of claim 1, further comprising
a circuit element mounted on a surface of said laminated body and connected

to at least one of said first inductor and said capacitor.

6. The high frequency laminated device of claim 1, further comprising
a second inductor pattern forming a second inductor provided between said
5 first and second sheets.